



AP1018

18V Dual H-Bridge Motor Driver IC

1. General Description

The AP1018 is a Dual H-Bridge small motor driver corresponding to the motor drive voltage 18V. Since the AP1018 has two output channels, it is capable of driving two DC motors or one stepper motor. It can be used up to peak current of 4.5A, so it can be used safely even with a motor that requires a large current at the start of driving.

Also it has under voltage detection and thermal shut down circuits as a protection circuit.

The AP1018 is housed in a high heat dissipation 24-pin QFN package (4mm x 4mm) with an exposed pad. It is a motor driver IC that realizes reduction of mounting area.

2. Features

- Control Supply Voltage 2.7 to 5.5V
- Logic Input Power Supply 1.62V to Control Supply Voltage (VC)
- Motor Drive Voltage 2 to 18V
- Maximum Output Current (DC) 1.3A (max)
- Maximum Output Current (Peak) 3.0A (Ta = 25°C, within 10ms in every 200ms)
4.5A (Ta = 25°C, within 5ms in every 200ms)
- H-Bridge On Resistance RON (TOP+BOT) = 0.36Ω (typ) (Ta = 25°C)
- Power Saving Function VM Power Consumption is less than 2μA (Ta = 25°C)
- Under Voltage Lockout Circuit (UVLO)
- Thermal Shutdown Circuit (TSD)
- Package 24-pin QFN (4.0mm x 4.0mm)

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4. Block Diagram

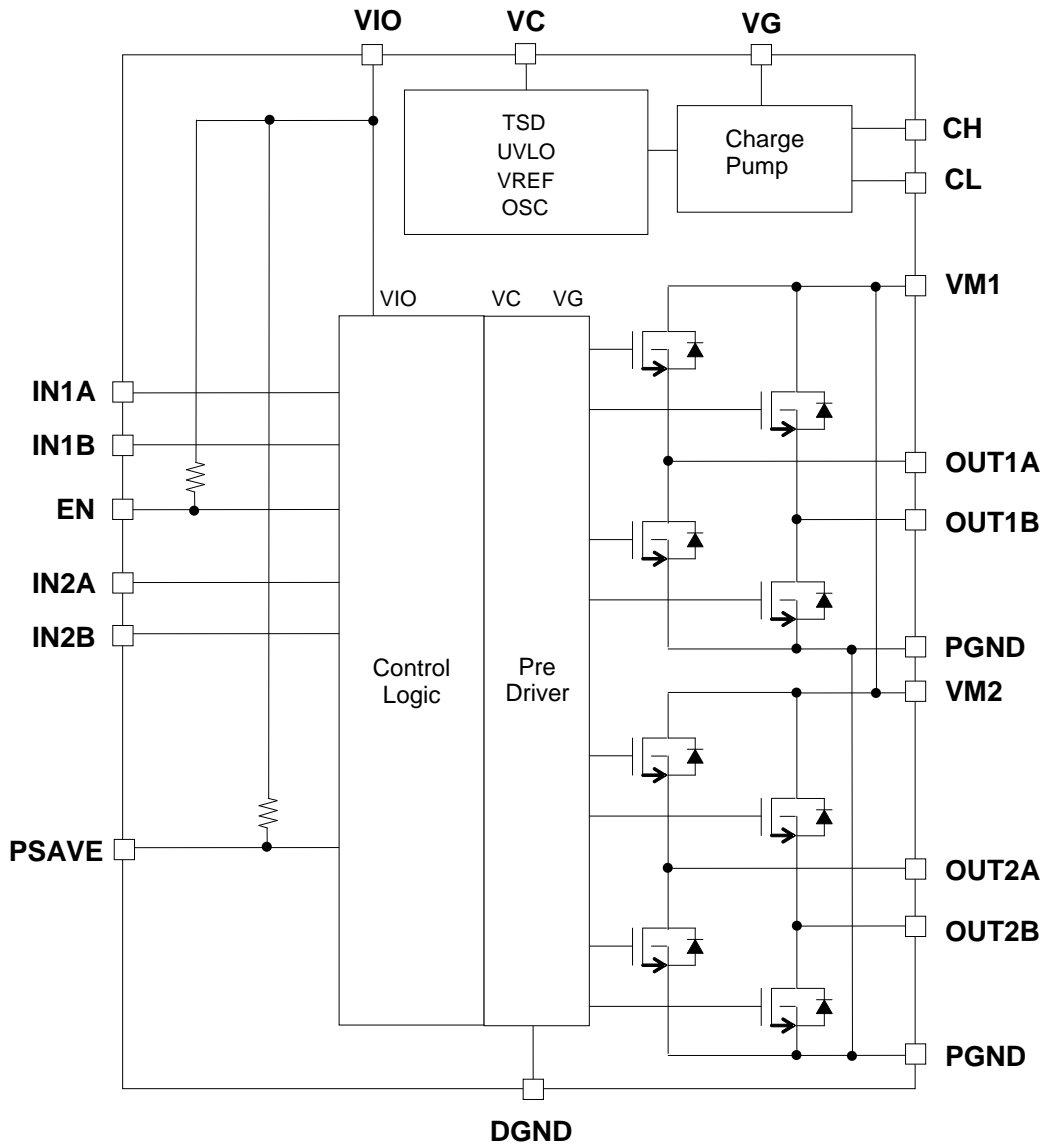
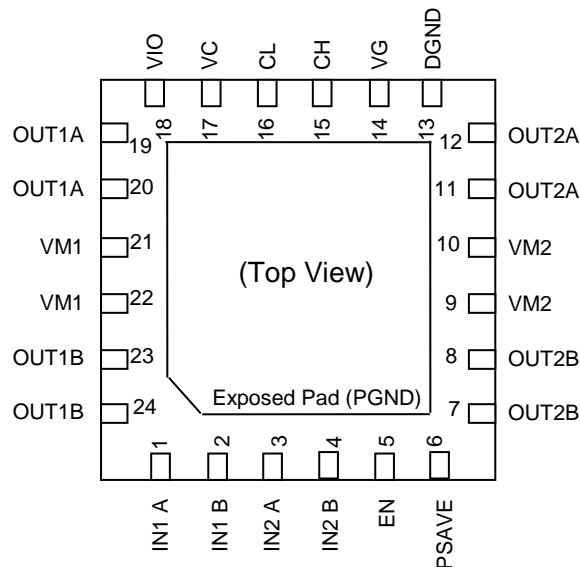


Figure 1. Block Diagram

5. Pin Configurations and Functions

■ Pin Configurations



■ Functions

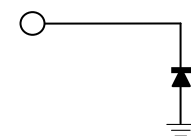
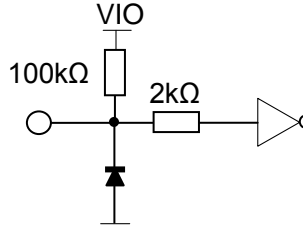
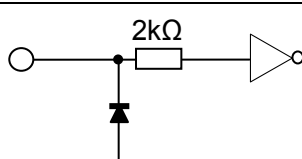
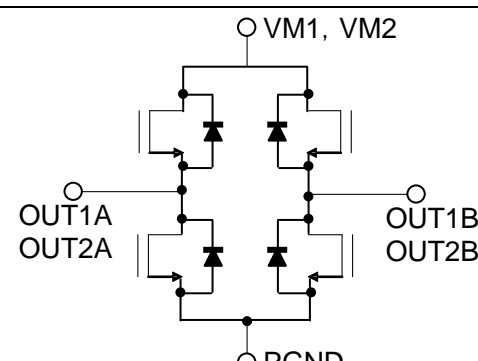
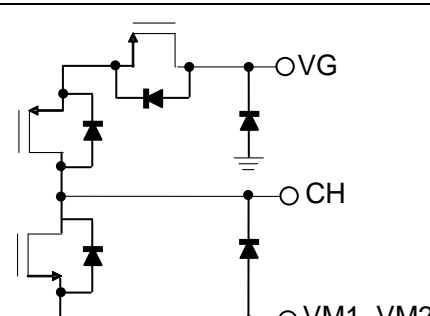
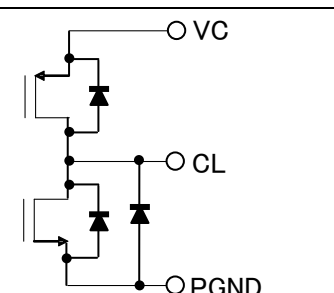
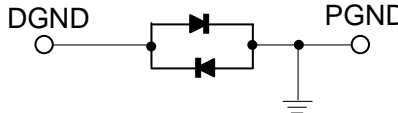
Pin Number	Name	I/O (Note 1)	Function	Note
14	VG	O	Connection Terminal for Stabilizing Capacitor	
15	CH	I/O	Connection Terminal for Charge Pump Capacitor	
16	CL	I/O	Connection Terminal for Charge Pump Capacitor	
21, 22	VM1	P	Motor Driver Power Supply 1	(Note 3)
19, 20	OUT1A	O	Motor Driver Output Terminal 1A	
23, 24	OUT1B	O	Motor Driver Output Terminal 1B	
Exposed Pad	PGND	P	Ground Terminal	(Note 2)
11, 12	OUT2A	O	Motor Driver Output Terminal 2A	
7, 8	OUT2B	O	Motor Driver Output Terminal 2B	
9, 10	VM2	P	Motor Driver Power Supply 2	(Note 3)
4	IN2B	I	Control Signal Input Terminal 2B	
3	IN2A	I	Control Signal Input Terminal 2A	
2	IN1B	I	Control Signal Input Terminal 1B	
1	IN1A	I	Control Signal Input Terminal 1A	
13	DGND	P	Ground Terminal	
5	EN	I	Output Enable Terminal	Built-in 100kΩ pull-up
6	PSAVE	I	Power Save Terminal	Built-in 100kΩ pull-up
18	VIO	P	Logic Input Power Supply Terminal	
17	VC	P	Control System Power Supply Terminal	

Note 1. I (Input pin), O (Output pin), P (Power pin)

Note 2. The exposed pad should be connected to the DGND pin for heat dissipation.

Note 3. VM1 (pin No.21 and 22) and VM2 (pin No.9 and 10) should be connected to the same power supply voltage.

■ Terminal Equivalent Circuits

Pin No.	Name	Function	Equivalent Circuits
18	VIO	Logic Input Power Supply	
17	VC	Control System Power Supply	
5 6	EN PSAVE	Logic Input (Built-in 100kΩ pull-up)	
1 2 3 4	IN1A IN1B IN2A IN2B	Control Signal Input	
21,22 9,10	VM1 VM2	Motor Driver Power Supply (VM1 (pin No. 21, 22), VM2 (pin No. 9, 10) to connect the same power supply voltage)	
19, 20 23, 24 11, 12 7, 8	OUT1A OUT1B OUT2A OUT2B	Motor Driver Output	
14 15	VG CH	Connection Terminal for Stabilizing Capacitor Connection Terminal for Charge Pump Capacitor	
16	CL	Connection Terminal for Charge Pump Capacitor	
13 Exposed Pad	DGND PGND	Digital Ground Power system ground	

6. Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit	Remarks
Control Supply Voltage	VC	-0.5	6.0	V	
Logic Input Voltage	VIO	-0.5	6.0	V	VIO ≤ VC (Note 6)
Motor Driver Operating Voltage	VM	-0.5	19	V	
VIO Level Terminal Voltage (PSAVE,EN,IN1A,IN1B,IN2A,IN2B)	Vterminal1	-0.5	5.5	V	
VM Level Terminal Voltage (OUT1A,OUT1B,OUT2A,OUT2B)	Vterminal2	-0.5	19	V	
VG, CH Terminal Voltage	Vterminal3	-0.5	25	V	
CL Terminal Voltage	Vterminal4	-0.5	6.0	V	
Maximum DC Output Current	IloaddcMD	-	1.3	A	OUTnA and OUTnB terminal
Maximum Peak Output Current	IloadpeakMD	-	3 4.5	A	OUTnA and OUTnB terminal within 10ms in 200ms within 5ms in 200ms
Power Dissipation	PD	-	1625	mW	Ta = 85°C (Note 5)
Operating Temperature Range	Ta	-30	85	°C	
Maximum Junction Temperature	Tj	-	150	°C	
Storage Temperature Range	Tstg	-65	150	°C	

Note 4. All above voltages are with respect to GND.

Note 5. This is calculated as $\theta_{JA}=40^{\circ}\text{C/W}$ using a 4-layer board. The exposed pad must be connected to GND. SEMI JEDEC JESD51-6 and JESD51-7 compliant boards are used.

Note 6. Logic Input Power Supply (VIO) needs to be turned on at the same time or earlier than Control System Power Supply (VC).

WARNING: Operation at or beyond these limits may result in permanent damage to the device. Normal operation is not guaranteed at these extremes.

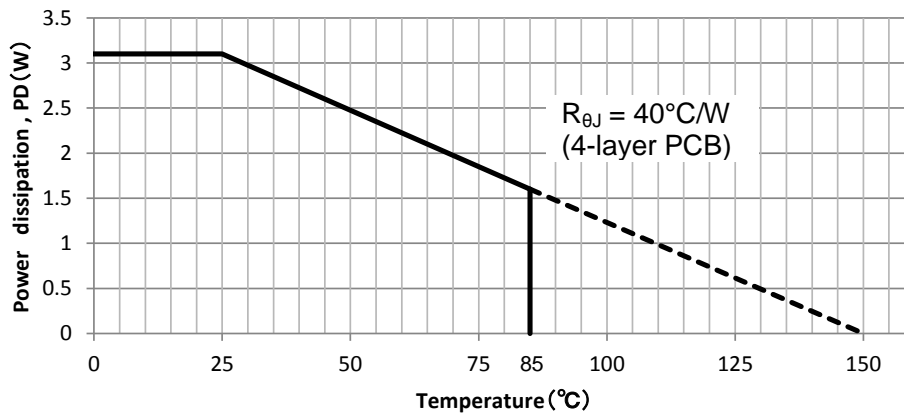


Figure 2. Maximum Power Dissipation

7. Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit
Control Supply Voltage	VC	2.7	3.3	5.5	V
Logic Input Voltage	VIO	1.62	1.8/3.3	VC	V
Motor Power Supply Voltage	VM	2.0	-	18	V
Input Frequency Range (50% duty)	Fin	-	-	200	kHz

8. Electrical Characteristics

(Ta = 25°C, VM = 15V, VC = 3.3V, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Charge Pump						
Charge Pump Voltage	VG	VG = VC + VM INnA = "L", INnB = "L"	18.0	18.2	18.3	V
Charge Pump wake up time	t _{VG}	VG = VC + VM - 0.3V CVG = 0.1uF	0.1	1	3	ms
UVLO						
VC under voltage lock out voltage	VC _{UV}		1.9	2.2	2.5	V
TSD						
Thermal shutdown temperature (Note 7)	T _{DET}		150	175	200	°C
Temperature hysteresis (Note 7)	T _{DETHYS}		20	30	40	°C
Quiescent Current						
VM quiescent current at no power	I _{VMNOPOW+}	VIO = VC = 0V	-	-	2	μA
VM quiescent current at Standby	I _{VMSTBY}	PSAVE = "L", EN = "H" INnA = "L", INnB = "L"	-	15	70	μA
VC quiescent current at Standby	I _{VCSTBY}	PSAVE = "L", EN = "H" INnA = "L", INnB = "L"	-	150	300	μA
VC quiescent current at power save	I _{VCPSAVE}	PSAVE = "H", EN = "H"	-	-	1	μA
VC quiescent current at PWM operation	I _{VCPWM}	INnA = 200kHz, INnB = "H"	-	1	2	mA
Motor Driver						
On-resistance 1 (High side or Low side)	R _{ON1}	VC = 3.3V, Iload = 100mA Ta = 25°C	-	0.18	0.25	Ω
On-resistance 2 (High side or Low side) (Note 7)	R _{ON2}	VC = 3.3V, Iload = 1.2A Ta = 25°C (Equivalent Tj = 85°C)	-	0.22	0.27	Ω
On-resistance 3 (High side or Low side) (Note 7)	R _{ON3}	VC = 3.3V, Iload = 1.2A Ta = 85°C (Equivalent Tj = 150°C)	-	0.27	0.32	Ω
Body diode forward voltage	V _{FMD}	I _F = 100 mA	-	0.8	1.2	V
Output delay time (INn:"H"→"L" to OUTn:"H"→"L") (Note 8)	t _{PDL}	tr = tf = 10ns	-	-	0.5	μs
Output delay time (INn:"L"→"H" to OUTn:"L"→"H") (Note 8)	t _{PDH}	tr = tf = 10ns	-	-	1.0	μs
Output delay time (INn:"L"→"H" to OUTn:Hi-Z→"H") (Note 8)	t _{PDZH}	tr = tf = 10ns	-	-	0.5	μs
Output delay time (INn:"H"→"L" to OUTn:"H"→Hi-Z) (Note 8)	t _{PDHZ}	tr = tf = 10ns	-	-	2.0	μs
H-bridge output pulse width (Note 8)	t _{PWO}	t _{PWI} = 1.0μs, tr = tf = 10ns	0.6	-	-	μs
Control logic						
Input High level voltage (INnA, INnB, EN, PSAVE)	V _{IH}	VIO = 1.62V~5.5V	0.7×VIO	-	-	V
Input Low level voltage (INnA, INnB, EN, PSAVE)	V _{IL}		-	-	0.3×VIO	V

Note 7. Not tested in production.

Note 8. Refer to [Figure 3](#).

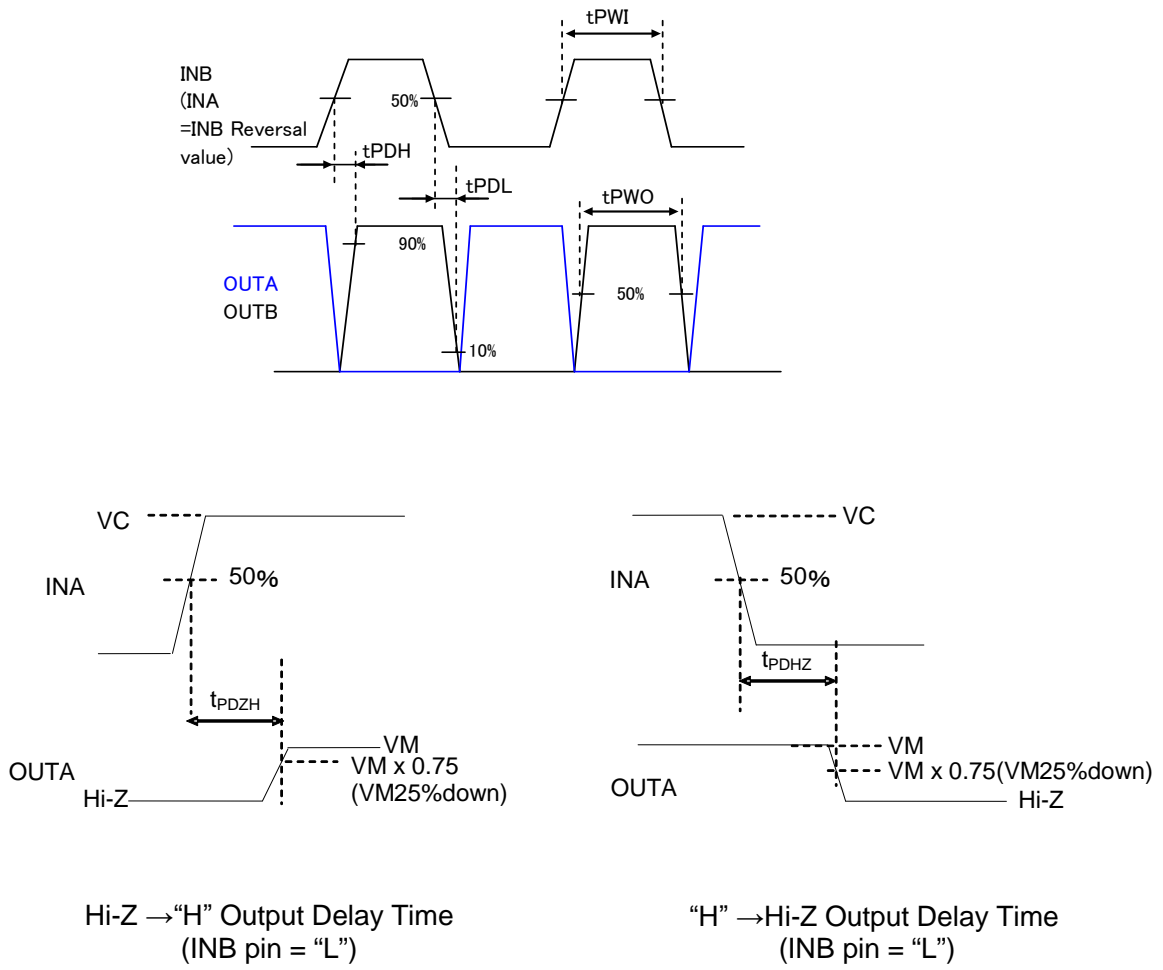


Figure 3. Timing Chart of Output Propagation Delay Time and Pulse Width

9. Functional Descriptions

9.1 Control Logic

Input and Output statuses of each operation mode are shown below. (X: don't care)

PSAVE	EN	Input		Output		Operation Mode
		INnA	INnB	OUTnA	OUTnB	
L	H	L	L	Hi-Z	Hi-Z	Standby
L	H	L	H	L	H	Reverse (CCW)
L	H	H	L	H	L	Forward (CW)
L	H	H	H	L	L	Brake
L	L	X	X	L	L	Brake
H	X	X	X	Hi-Z	Hi-Z	Power Save (Note 9)

Note 9. TSD, UVLO, Internal charge pump and VREF circuits stop operation.

9.2 The Basic Configuration of The Motor Driver Unit

The AP1018 has the N-channel LDM CMOS FETs for both high and low sides of the output stage, so that small package can be adopted. The high-side FET is driven by VG voltage. $VG = VM + VC$ is generated by the charge pump. VG voltage reaches the target value within 1ms (typ.) after the charge pump starts operation. The charge pump operates at 360kHz (typ). The low-side FET is driven by the VC voltage.

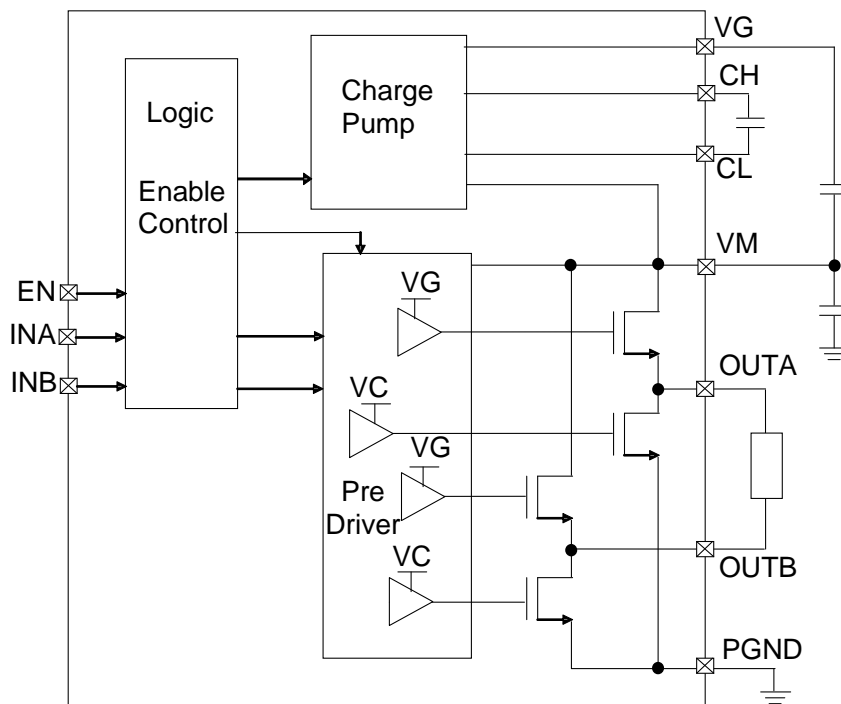


Figure 4. Equivalent Circuit of Motor Driver Block

The OSC block supplies a drive pulse to the charge pump. Logic input buffer is operated by the power supply from the VIO pin. Logic input power supply (VIO) should be turned on at the same time or earlier than the Control system power supply (VC). Logic Input Power Supply (VIO) is Control System Power Supply (VC) and turned on at the same time or earlier. (With applications such as the VIO is turned on later than the VC, it is recommend to connect a pull-up resistor about 500kΩ between the VIO and the VC pins to avoid an indefinite state of the circuit)

9.3 Protection Functions

The AP1018 has penetration current prevention, thermal shutdown and under voltage detection circuits.

• Penetration Current Prevention Circuit

MOSFETs are turned off for both high side and low side during the dead time period that is when the penetration current prevention circuit is in operation. The dead time is included in the H-Bridge output delay time of the electrical characteristics. Figure 5 shows the signal timing images.

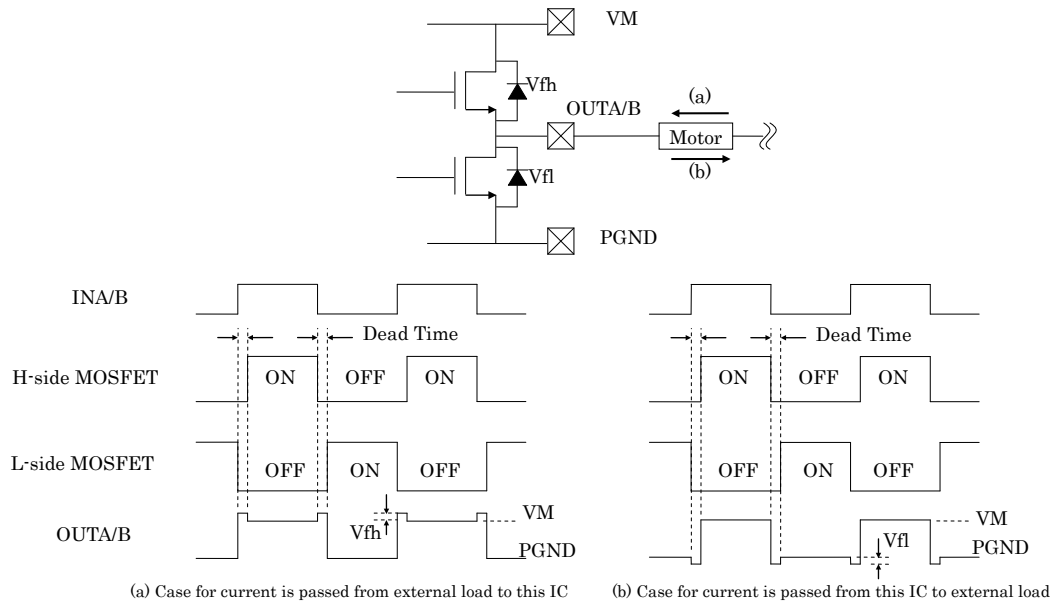


Figure 5. Difference In Output Terminal By Load Current Direction

• Thermal Shut Down (TSD)

The AP1018 prevents damages from self-heating by setting OUTA and OUTB outputs Hi-Z when abnormal high temperature is detected. The AP1018 is able to return to normal operation as soon as the temperature drops to the level lower than the bottom detection threshold.

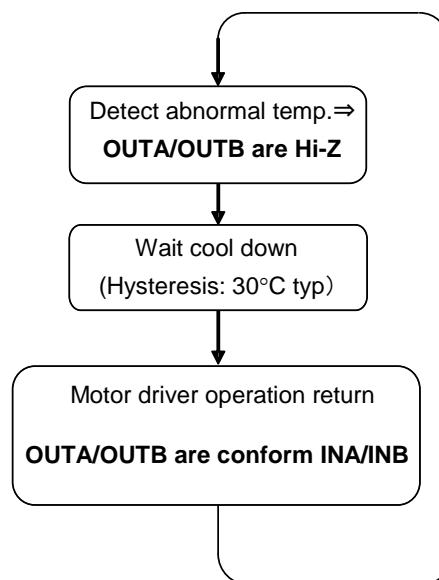


Figure 6. Detection of Abnormal Heat and Returning Normal Operation

• Under Voltage Detection Circuits

The H-bridge driver outputs become high-impedance by the under-voltage detection circuit (UVD) when the control power supply voltage (VC) is lower than the specified value.

After the low-voltage detection, the H-bridge driver will be operational when the control power supply voltage (VC) exceeds the value of specified voltage $VC_{UV} + \text{hysteresis voltage } VC_{UVHYS}$ (0.08Vtyp).

□ Timing Chart

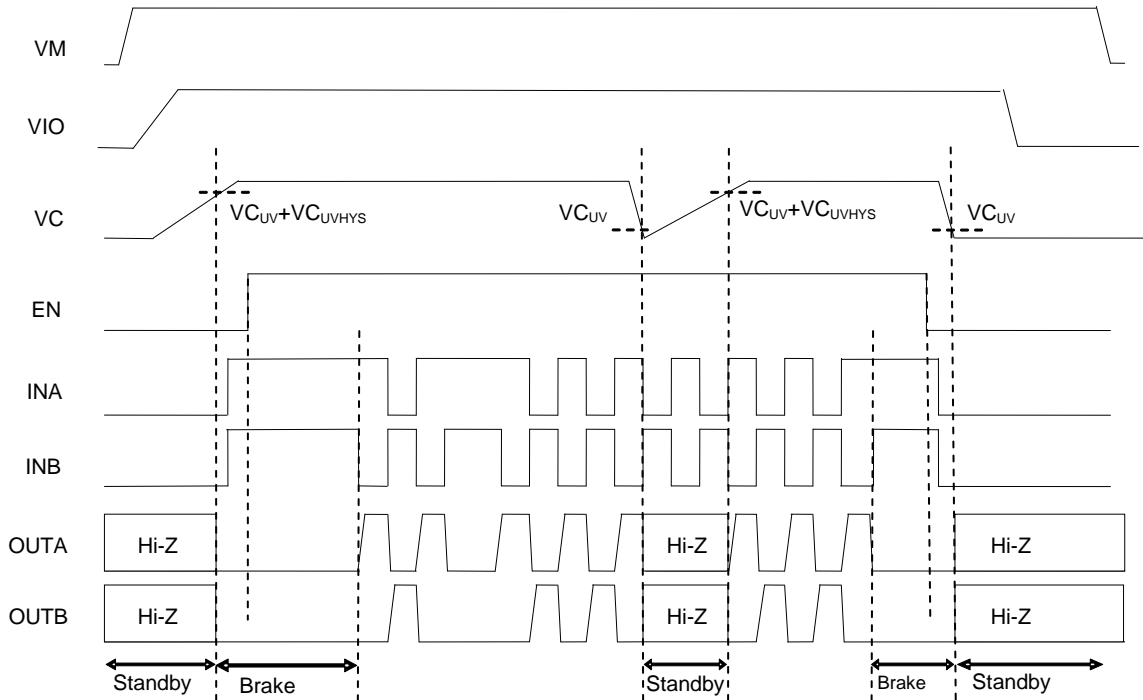


Figure 7. Timing Chart of Input and Output (In Case of Under Voltage Detection)

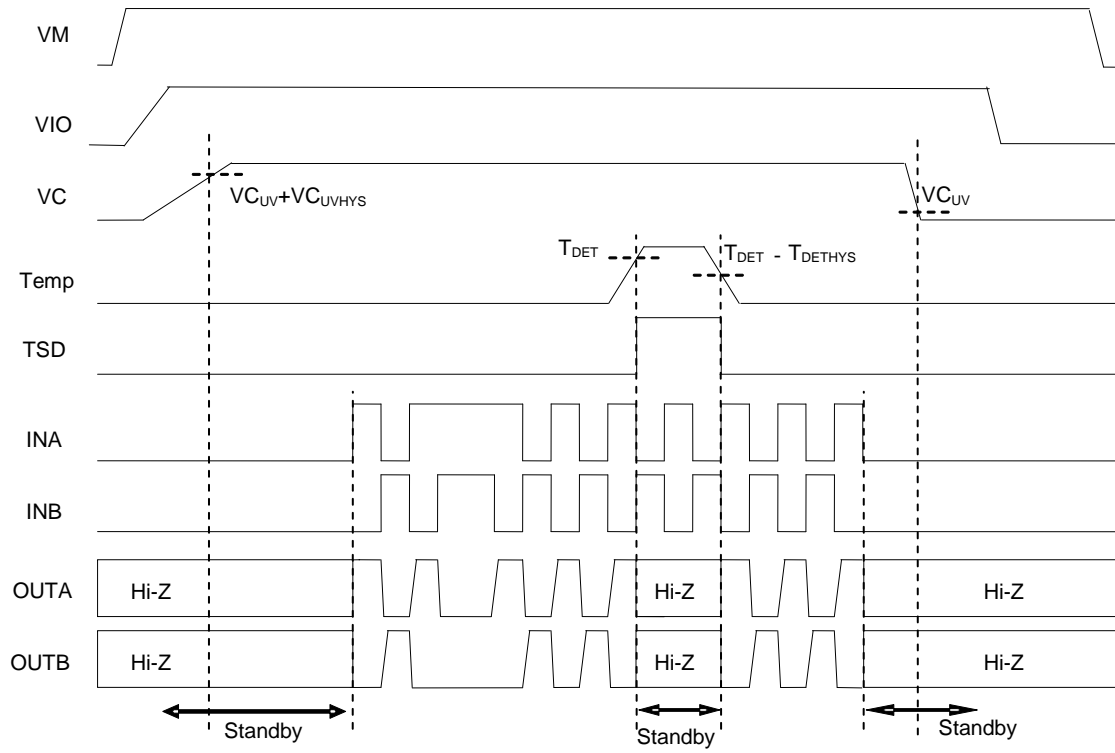


Figure 8. Timing Chart of Input and Output (In Case of TSD Detection)

10. Recommended External Circuit

■ Recommended External Circuit

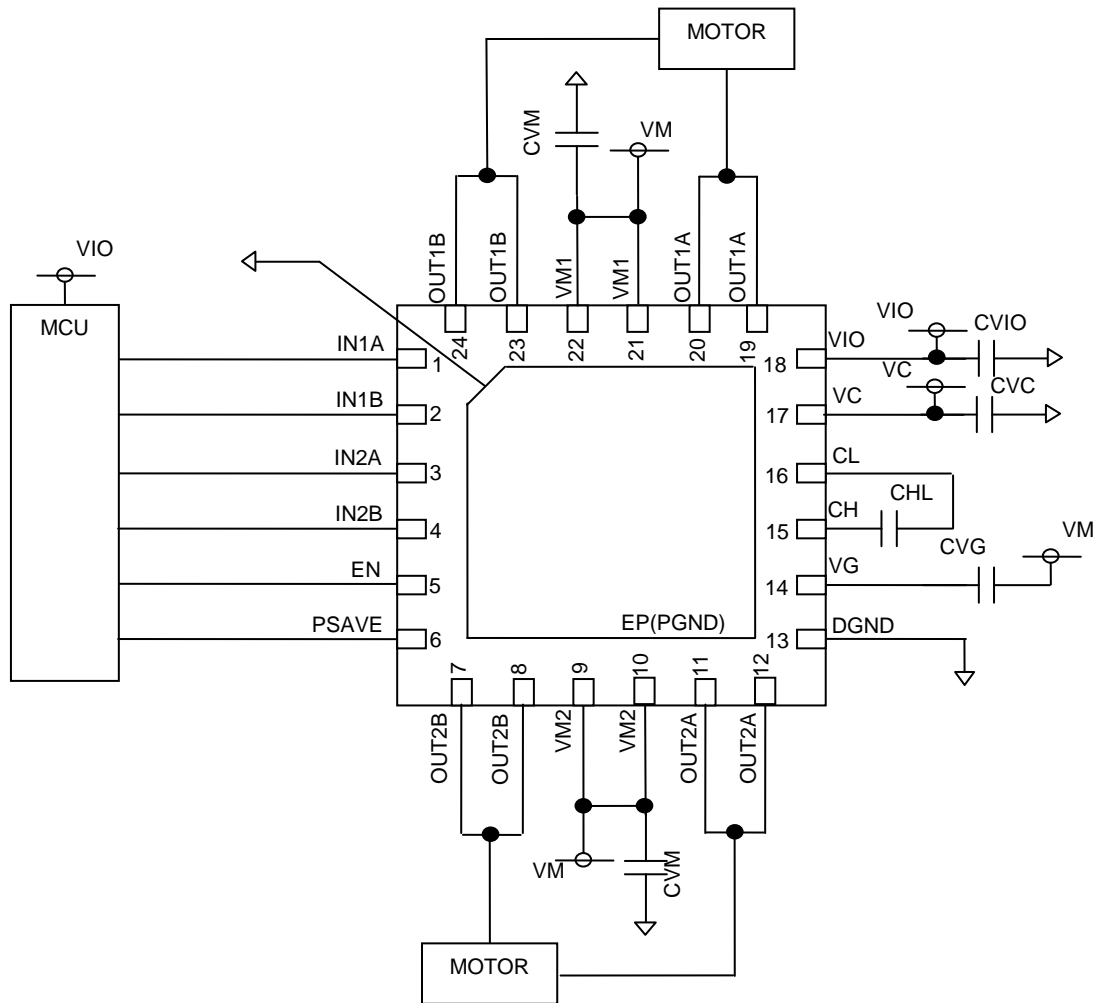


Figure 9. Recommended External Circuit

■ Recommended External Components

Items	Symbol	min	typ	max	Unit	Remark
Motor Driver Power Supply (decoupling capacitor)	CVM	1.0	-	-	μF	Ceramic Capacitor (Note 10)
VC Control Power Supply (decoupling capacitor)	CVC	0.1	1.0	-	μF	
VIO Control Power Supply (decoupling capacitor)	CVIO	0.1	1.0	-	μF	
Charge Pump Capacitor 1	CVG	0.047	0.1	0.22	μF	Ceramic Capacitor
Charge Pump Capacitor 2	CHL	0.047	0.1	0.22	μF	Ceramic Capacitor

Note 10. Above values are examples. Please choose appropriate external components for your system board.

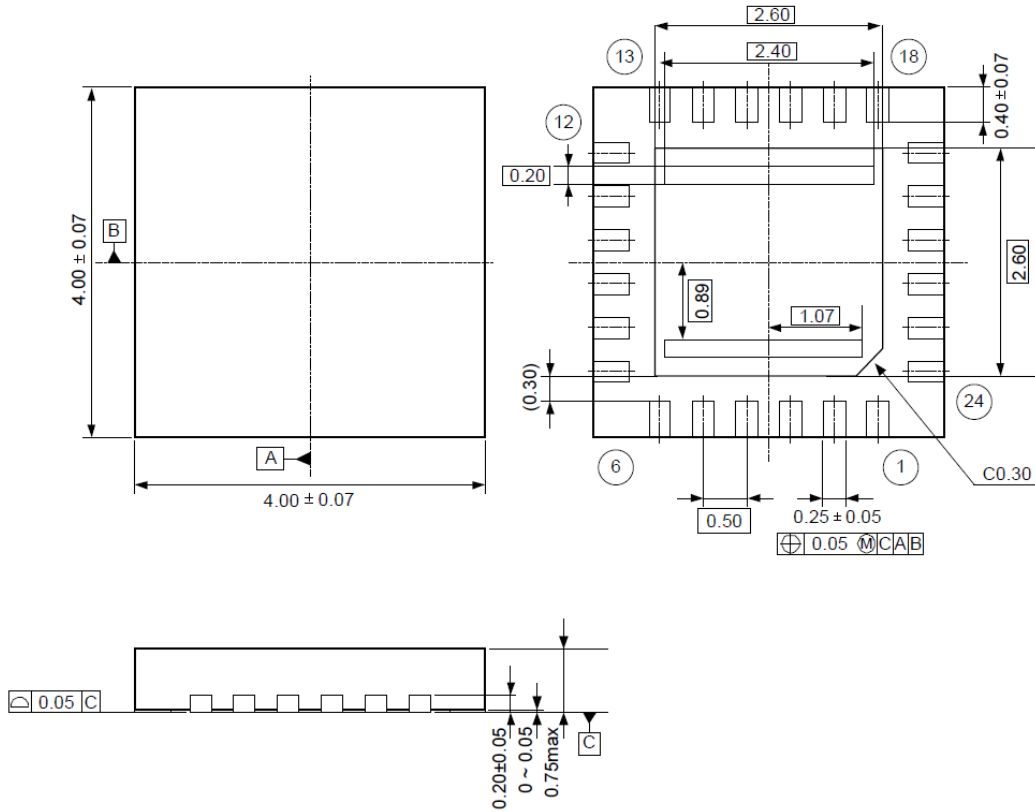
Note 11. VM1 (pin No. 21 and 22) and VM2 (pin No. 9 and 10) should be connected to the same power supply voltage.

Note 12. The exposed pad should be connected to the DGND pin for heat dissipation.

11. Package

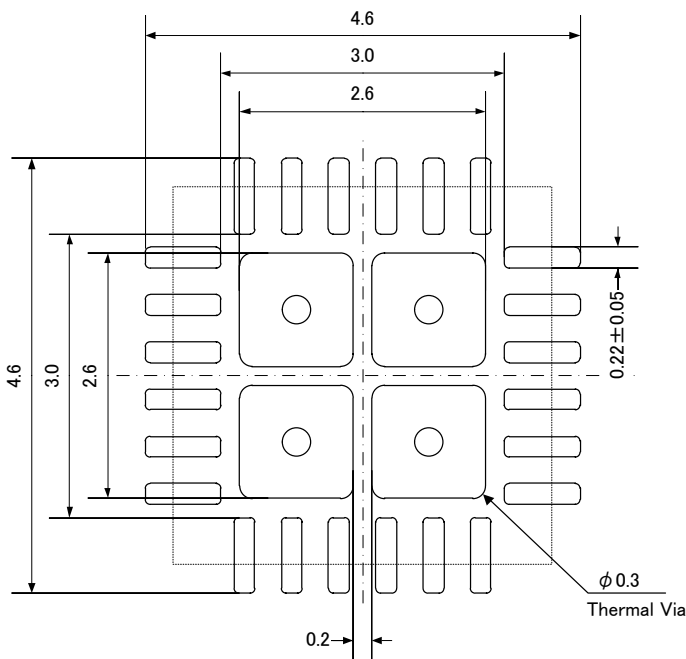
■ **Outline Dimensions**

24-pin QFN (Unit mm)



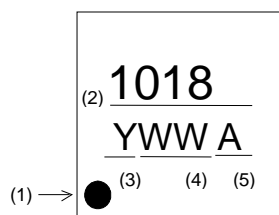
■ **Recommended Land Pattern**

AP1018AEN: 24-pin QFN Package



[unit: mm]

■ Marking



- (1) No.1 pin Indication
- (2) Market No
- (3) Year Code (last digit of the year)
- (4) Week Code
- (5) Management Code

12. Ordering Guide

AP1018AEN

-30 ~ 85°C

24-pin QFN

13. Revision History

Date (YY/MM/DD)	Revision	Page	Contents
17/05/29	00	-	First Edition

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